

**AMENDMENTS TO THE SPECIFICATION**

Please replace paragraph [0027] with the following amended version:

[0027] Figures 2a-2g and 3a-3g show various views of the lead frame connectors 12 and 22 of Figures 1a and 1b. U.S. Patent Application Serial No.       , 10/809,992, entitled “Lead Frame for Connecting Optical Sub-Assembly to Printed Circuit Board,” filed on the same day as the present application, is incorporated herein by reference and includes additional details of the structural features and electrical performance of the lead frame connectors illustrated in the drawings that accompany the present patent application.

Please replace paragraph [0029] with the following amended version:

[0029] According to one embodiment, the method of manufacturing lead frame connectors 12 and 22 is performed using a reel-to-reel insert injection molding process. U.S. Patent Application Serial No.       , 10/810,041, entitled “Methods of Manufacturing Lead Frame Connector for Connecting Optical Sub-Assembly to Printed Circuit Board,” filed on the same day as the present application, is incorporated herein by reference and includes additional details of methods of manufacturing the lead frame connectors that can be used to manufacture optical transceiver modules according to the present invention. The foregoing patent application also describes techniques for reducing undesirable RF responses during the process of manufacturing the lead frame connectors 12 and 22.